# **Equipment Information Sheet PT770 Etcher - Right Side (III-V)**

Manager: Tom Pennell 607-254-4309 Calls to staff phones will be automatically forwarded to Backup: Jeremy Clark 607-254-6487

their cell phones during accessible hours. At other times leave a message or send them an email.

#### SAFETY

- Chlorine and Methane chemistries used
- User must remain in the lab while tool is in operation

#### **USAGE RESTRICTIONS**

- Users must remove photoresist edge bead from full 4 inch wafers.
- pieces must be mounted to sapphire wafer.

#### SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

• Maximum 4 hour block reservations anytime. Maximum 12 houres reserved in advance at any time per person. No consecutive research group reservations. Users may use any amount of unreserved time.

## MATERIALS COMPATIBILITY CATEGORY

#### Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

### **Additional Material Restrictions and Exceptions**

- Photoresist, oxide, nitride, nickel masking only
- Photoresist mask edge bead must be removed (5mm ring) if using 100mm wafers
- Limited metal masking allowed see tool manager

Last Updated: 12/20/2022